



UNIVERSITY OF
BIRMINGHAM

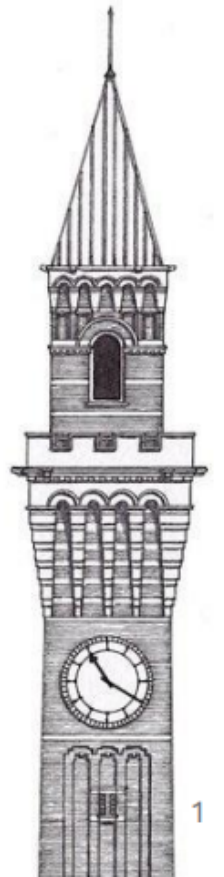


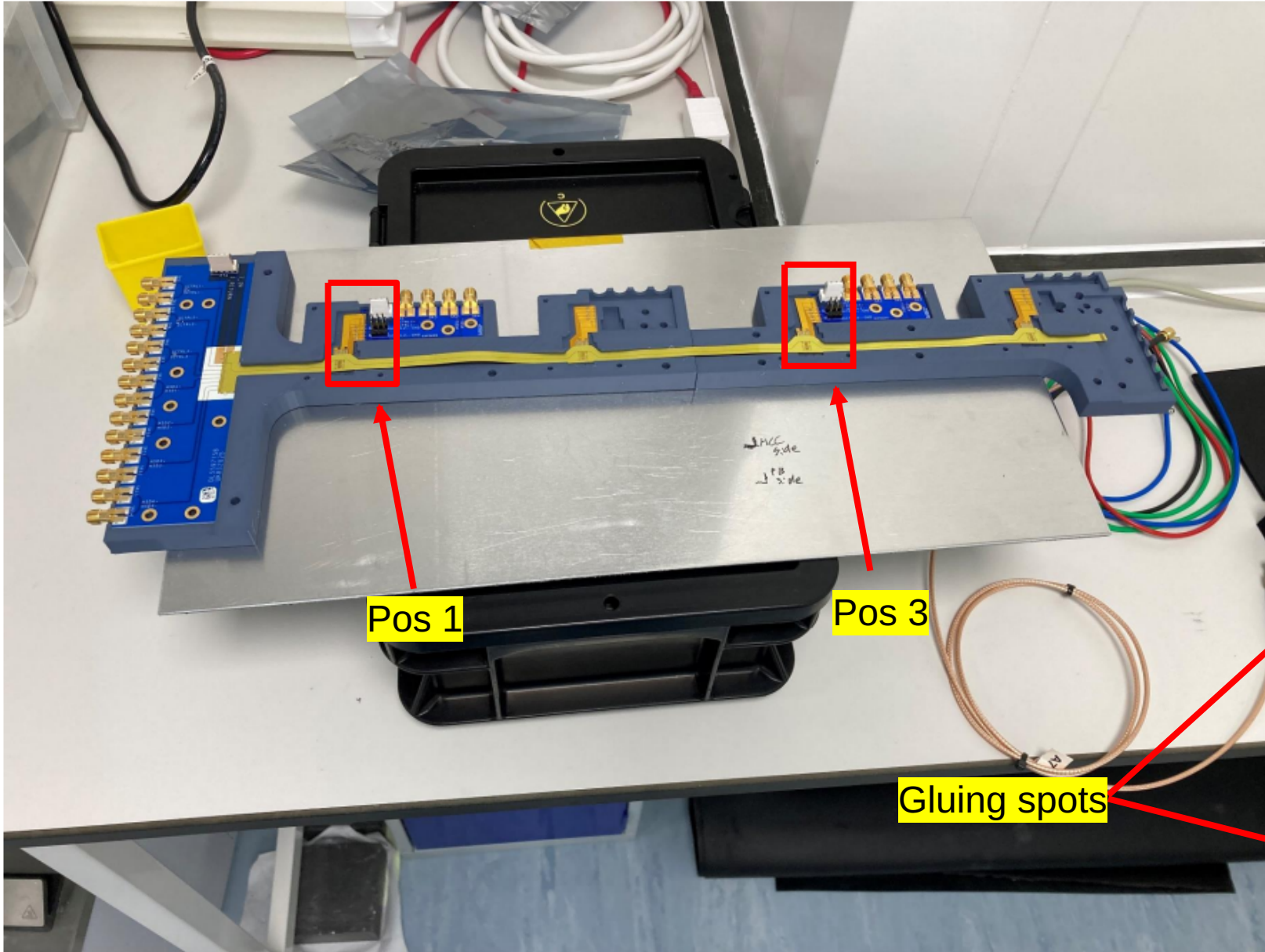
Sp-Tap Bonding M-FPC and B-Fpc

Eve Tse

SVT DSC meeting

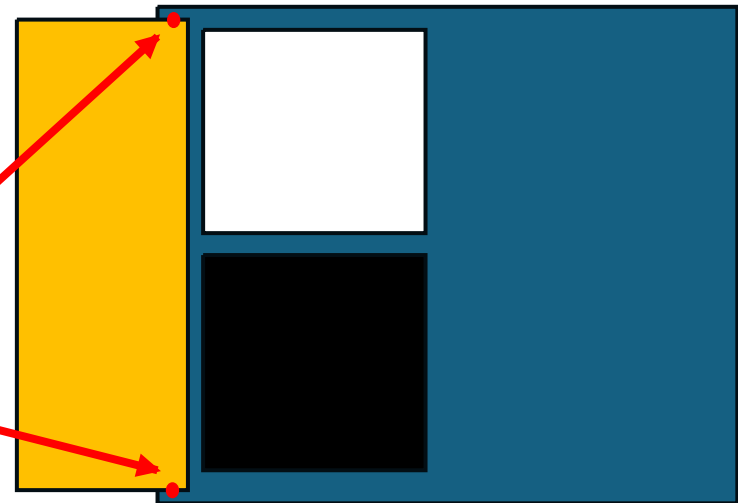
Tue, 14th April 2026





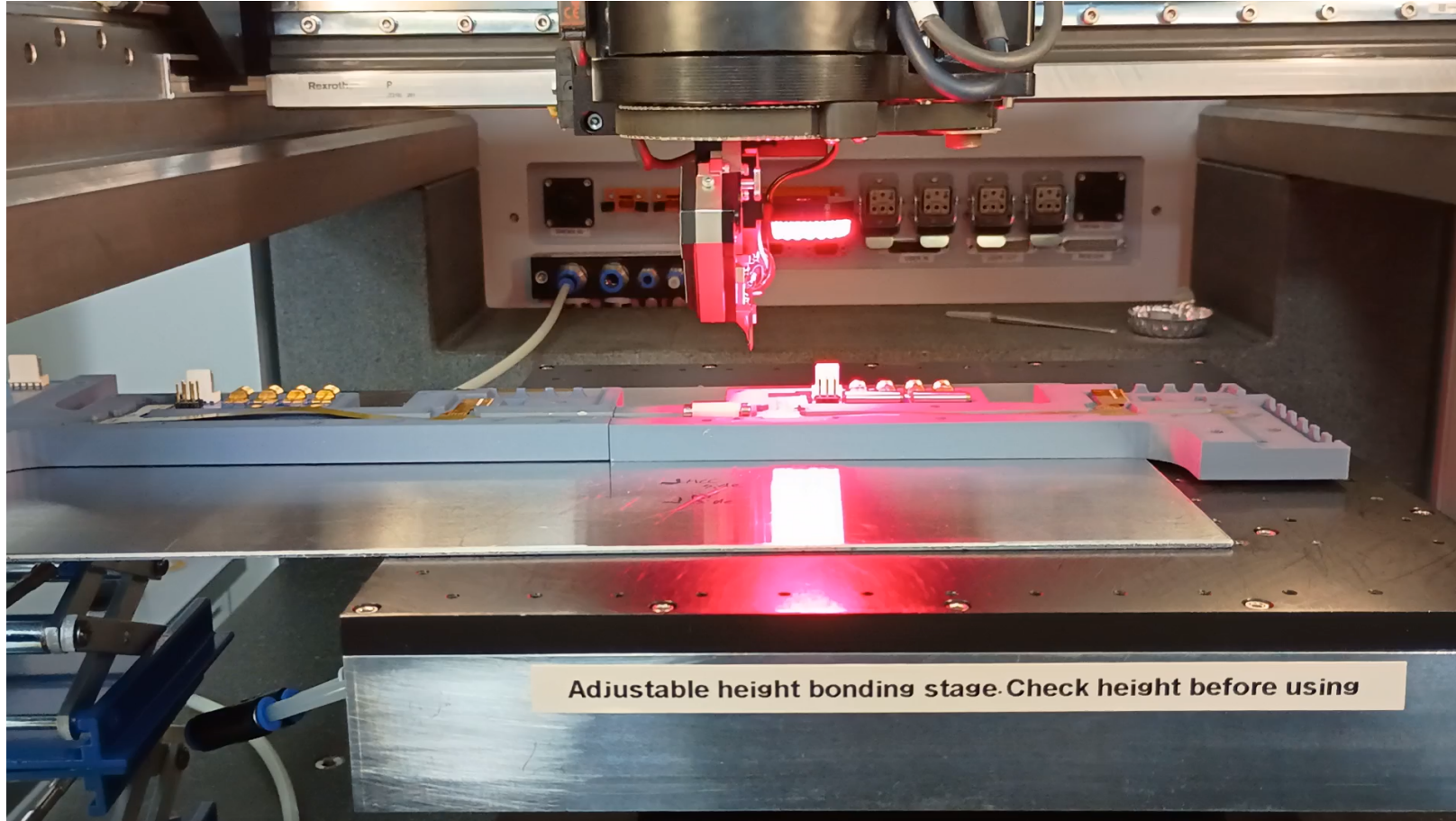
Bond pads taken up whole width of B-FPC & PCB only slightly wider than B-FPC make gluing prior to bonding very difficult

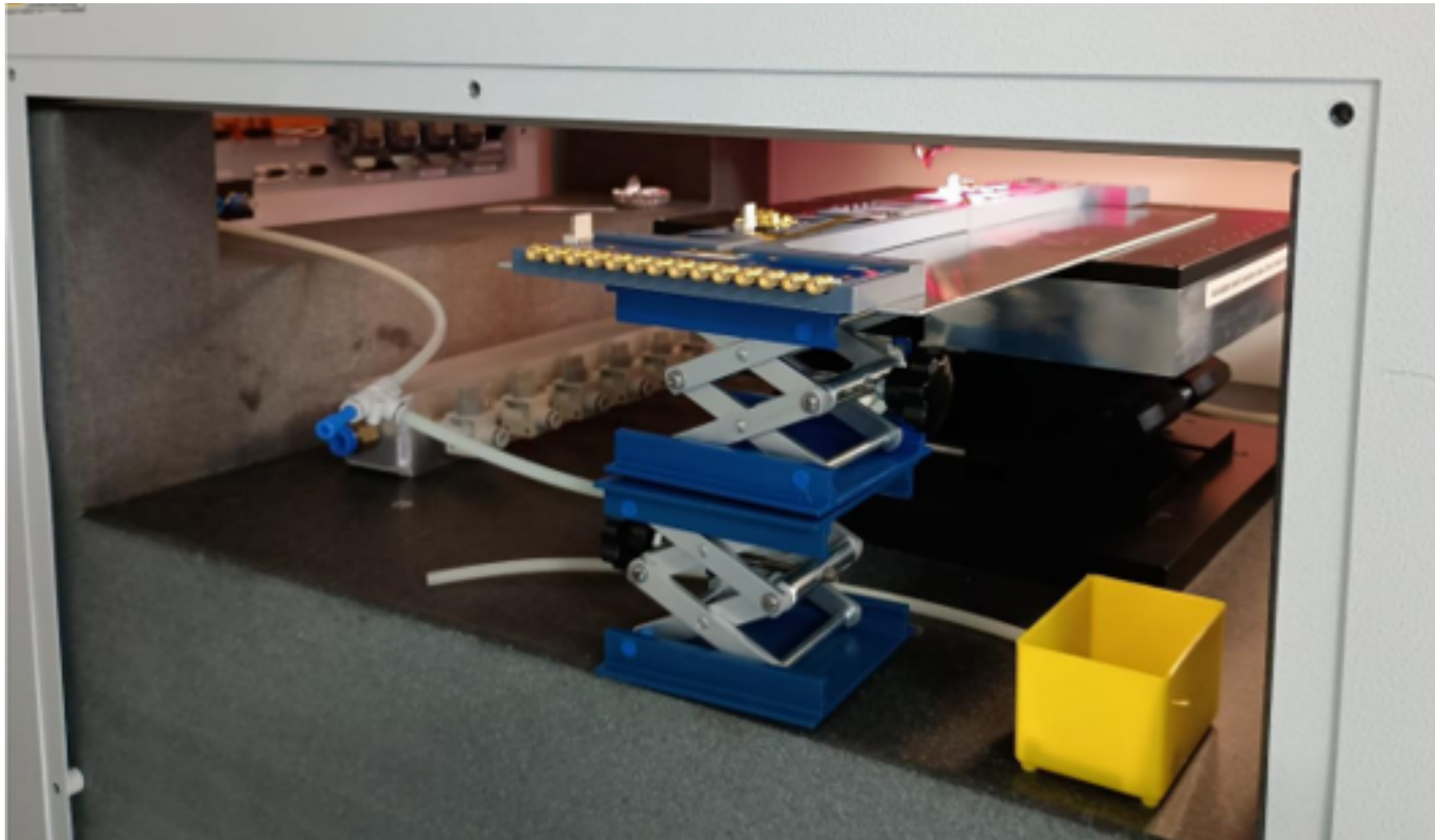
Glue can get onto bond pads and jig easily





B-FPC Bonding Challenge

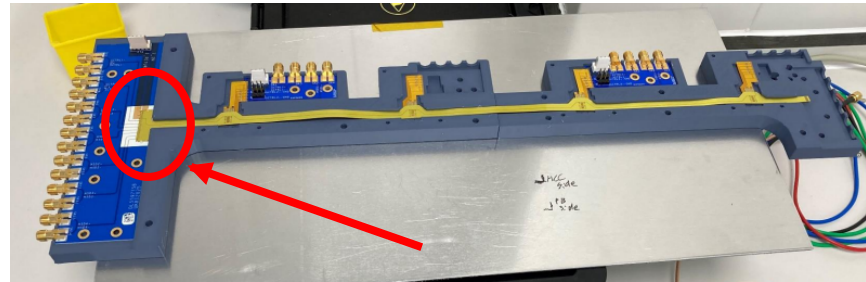




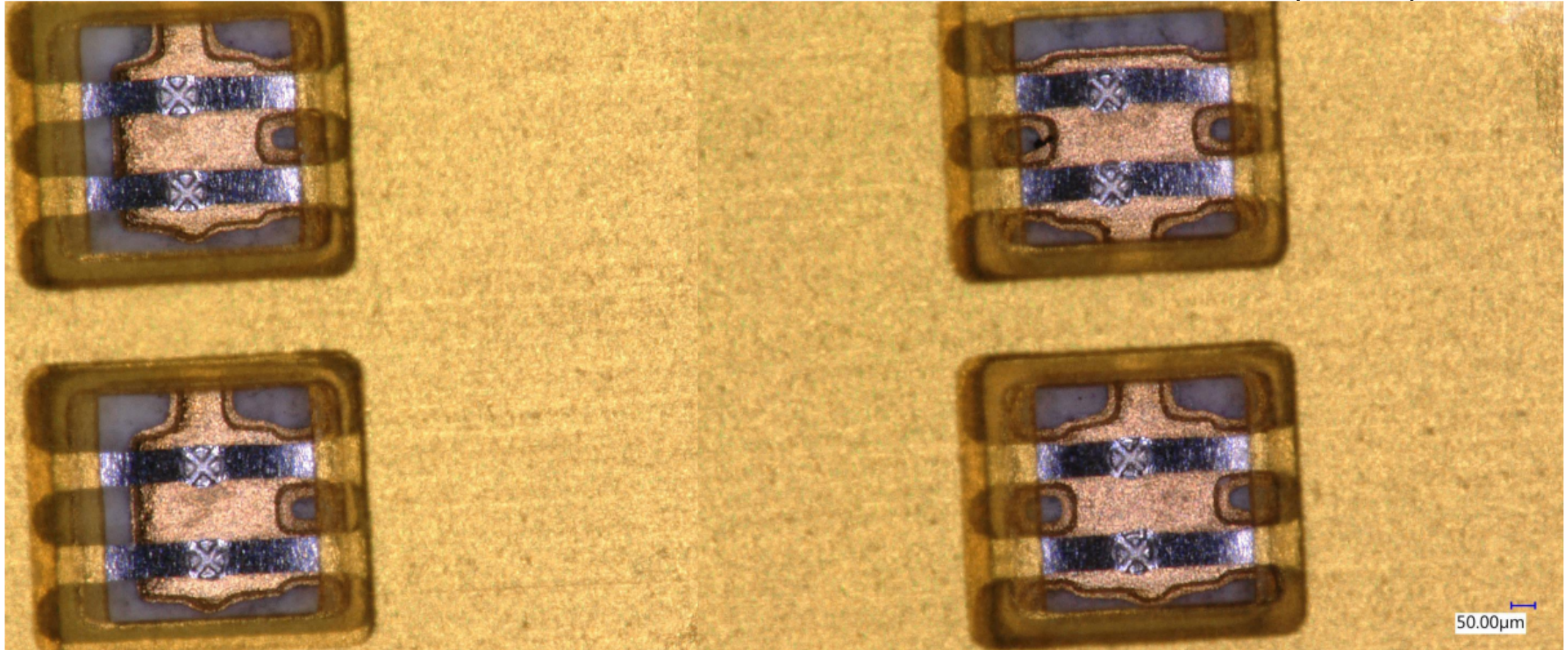
- Side Panel of the wirebonder needs to be removed
- Extra support structure needs to be installed to hold the rest of free hanging FPC while bonding



M-FPC bonding

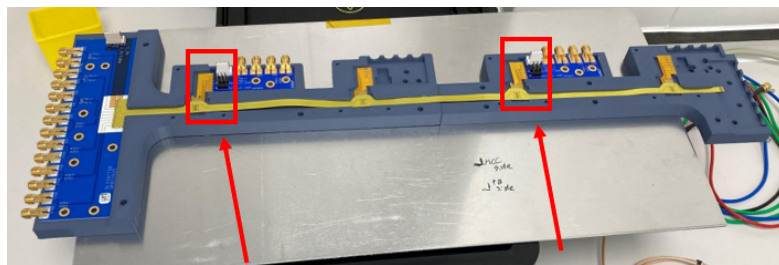


Easier gluing, better results
(Pictures for all the rest of
the bonds are included in
back-up slides)

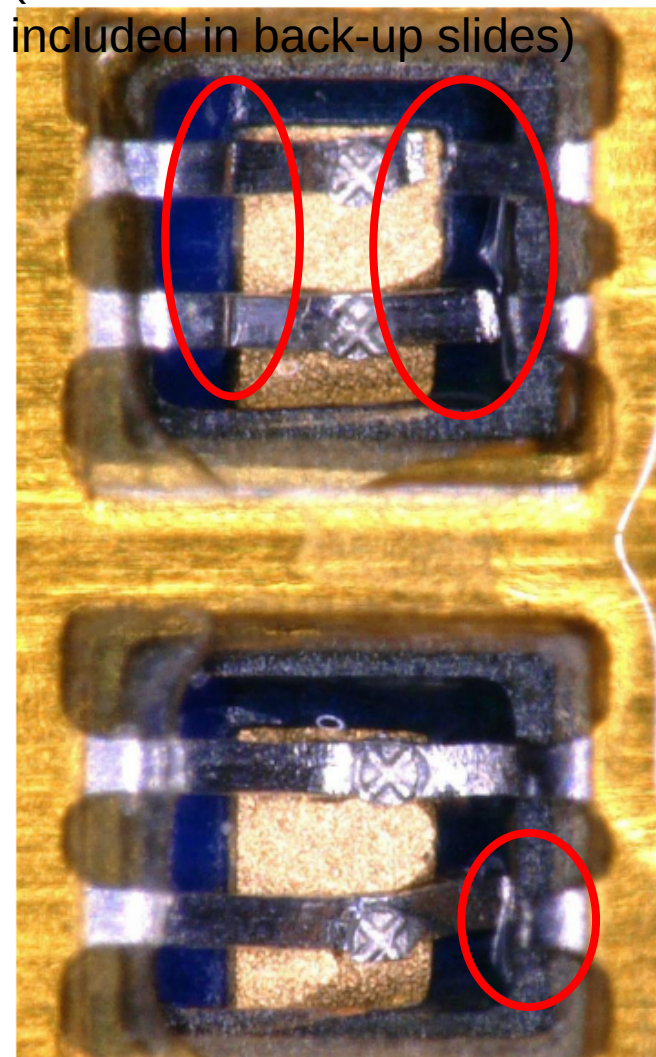
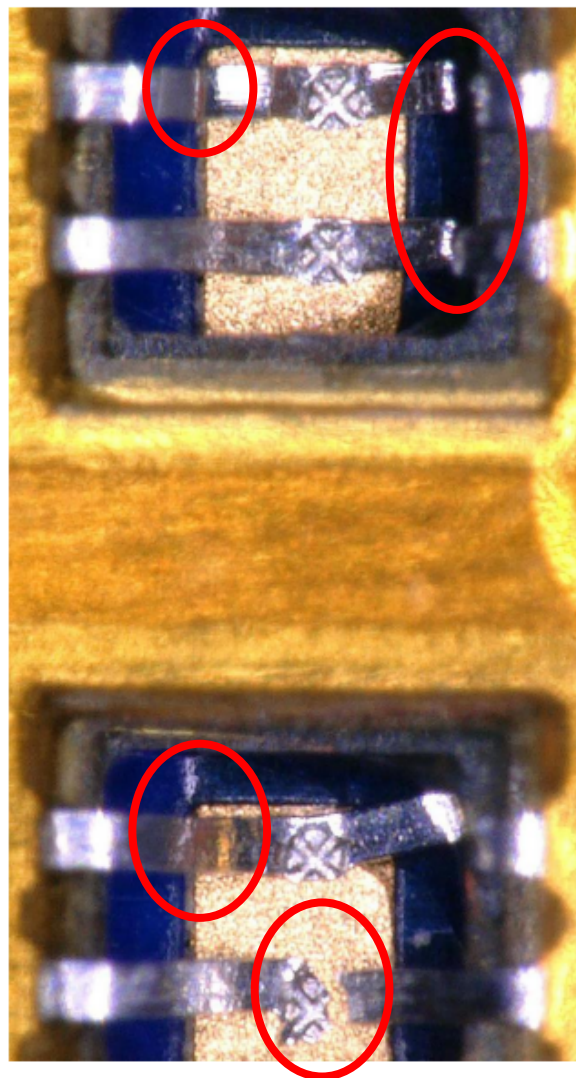
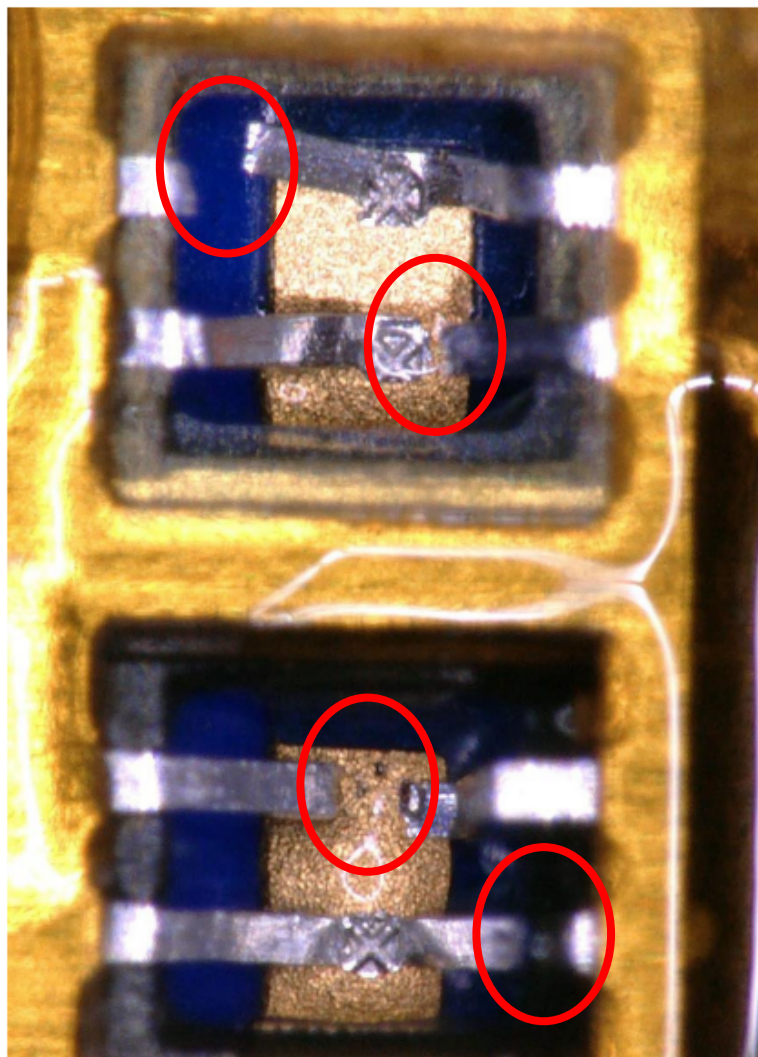




B-FPC



More challenging gluing, less guaranteed
(Pictures for all the rest of the bonds are included in back-up slides)





Thank you

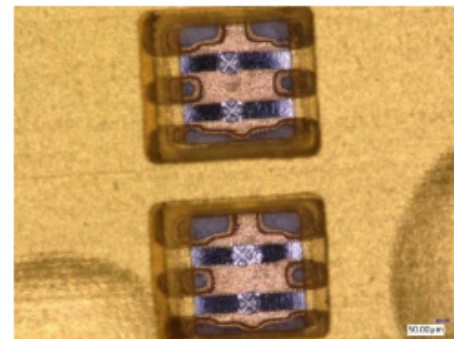
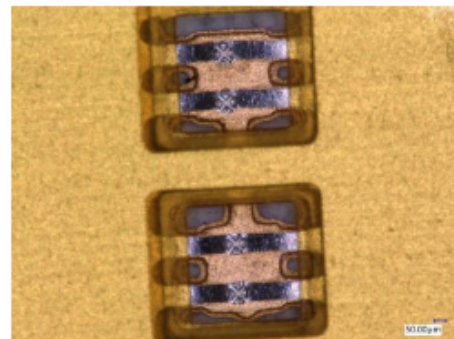
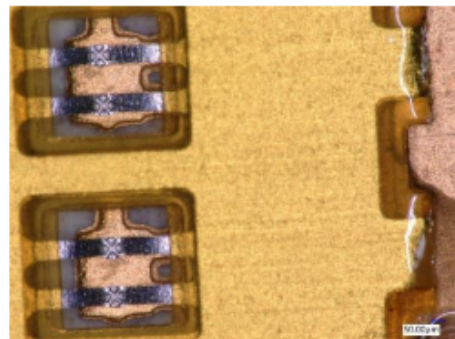
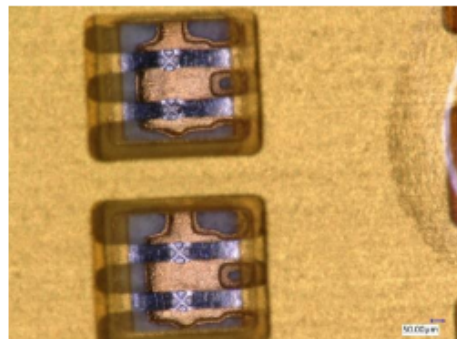
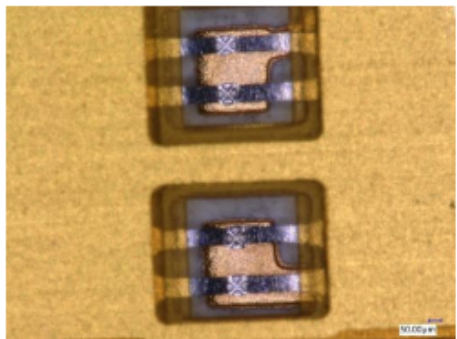
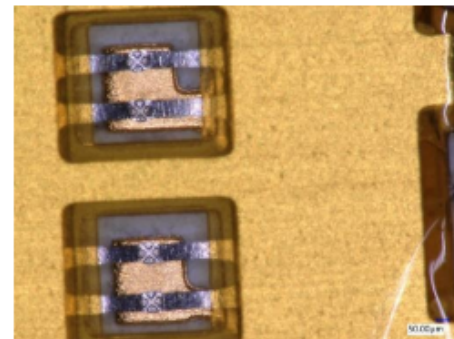
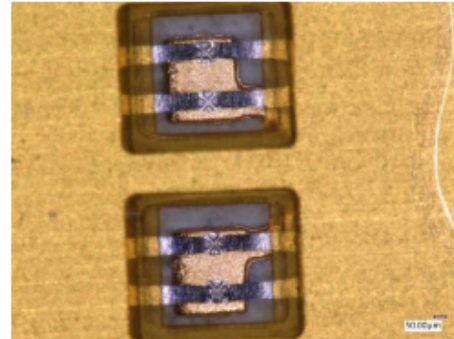
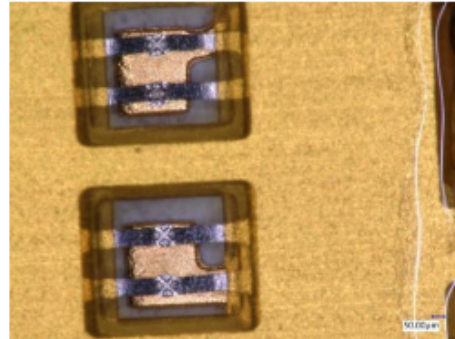
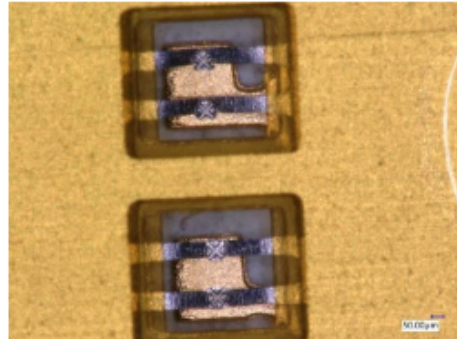
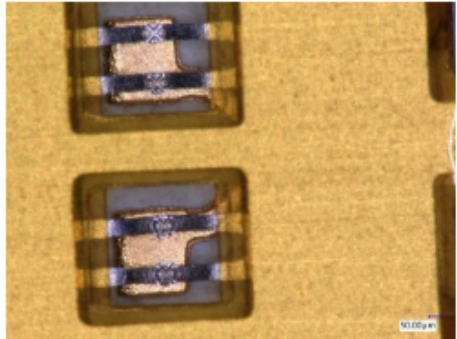
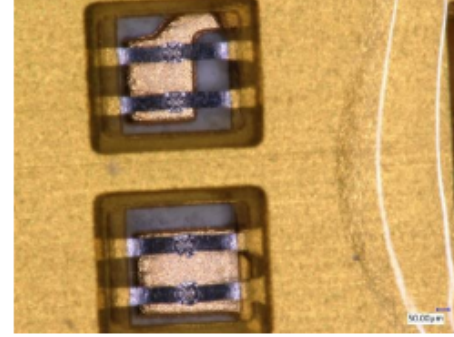
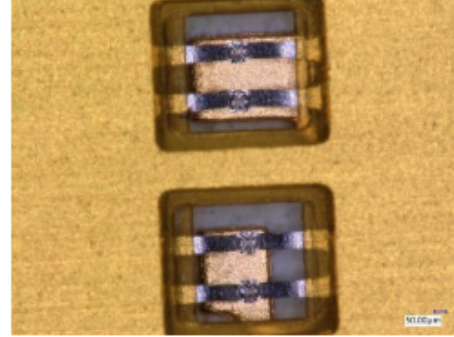
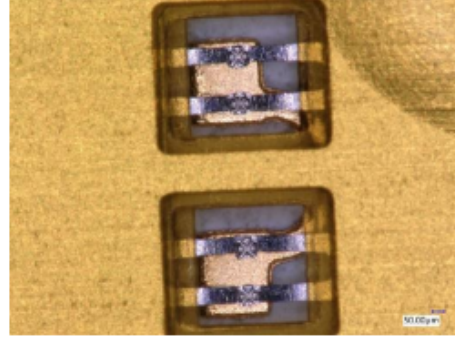
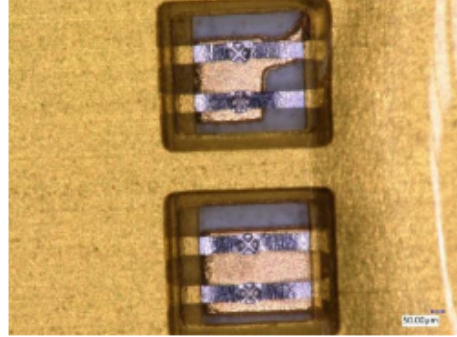
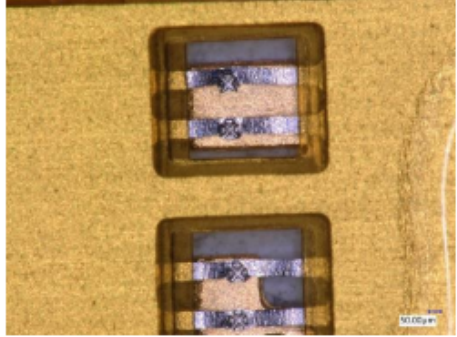
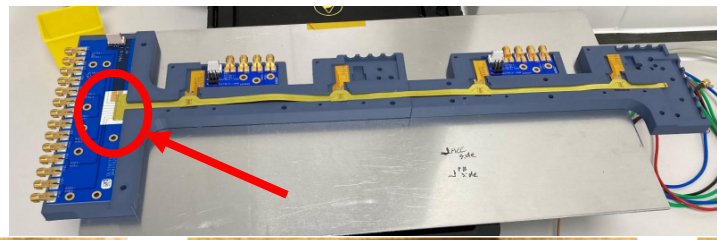


Back up slides



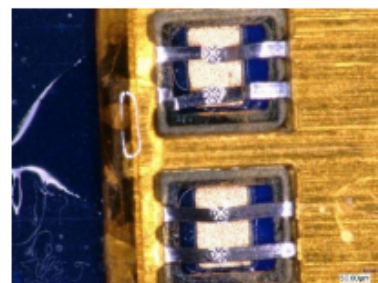
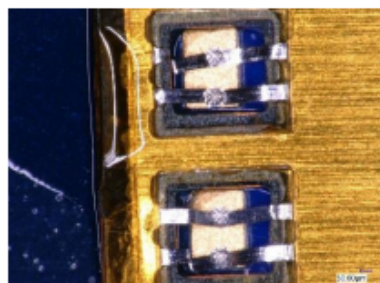
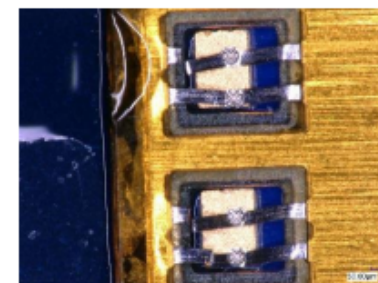
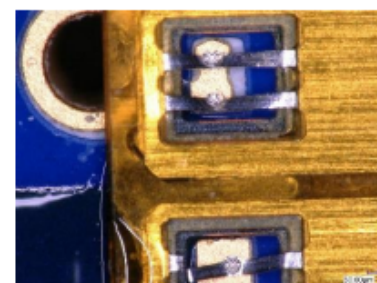
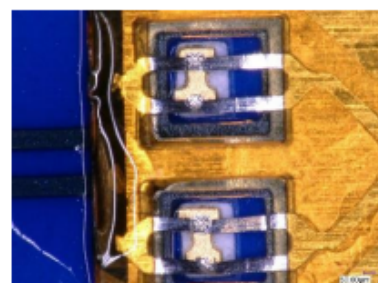
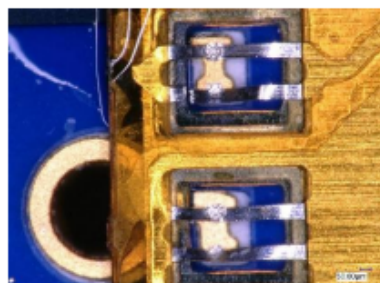
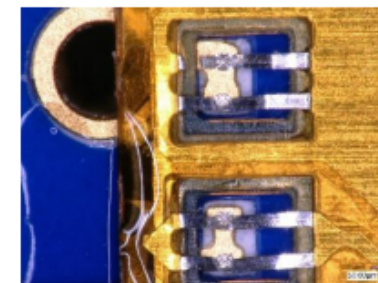
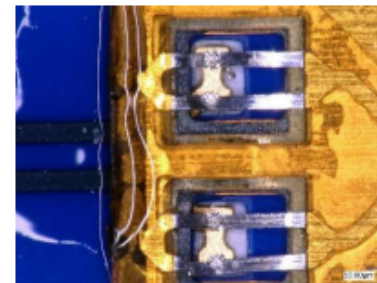
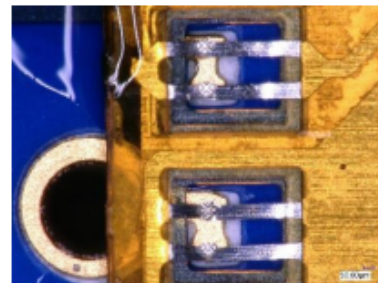
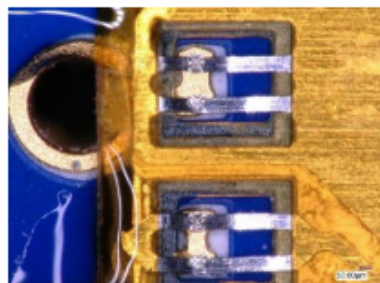
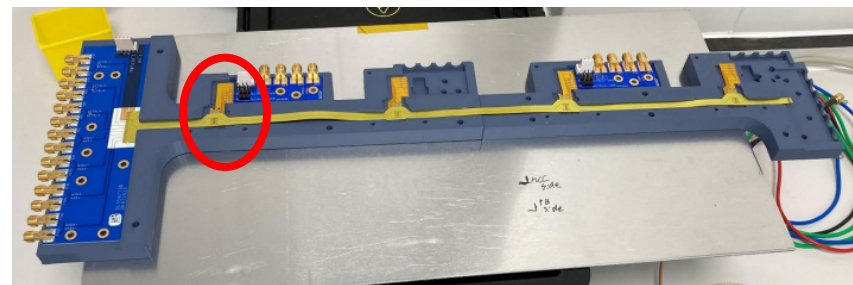
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M-FPC





B-FPC Position 1





B-FPC Position 3

